

L Number	Hits	Search Text	DB	Time stamp
1	196866	mold	USPAT; US-PGPUB	2004/03/18 16:02
2	295480	insert	USPAT; US-PGPUB	2004/03/18 15:55
3	422304	injection	USPAT; US-PGPUB	2004/03/18 15:55
4	138097	wafer	USPAT; US-PGPUB	2004/03/18 16:01
5	83359	masking	USPAT; US-PGPUB	2004/03/18 15:55
6	233471	etch\$3	USPAT; US-PGPUB	2004/03/18 15:55
7	273061	mask\$3	USPAT; US-PGPUB	2004/03/18 15:55
8	523095	mold\$3	USPAT; US-PGPUB	2004/03/18 15:56
9	4017	wafer and etch\$3 and mask\$3 and mold\$3	USPAT; US-PGPUB	2004/03/18 16:03
10	867	(wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.	USPAT; US-PGPUB	2004/03/18 16:48
11	622457	wafer substrate	USPAT; US-PGPUB	2004/03/18 16:01
12	100827	etch\$3 with (wafer substrate)	USPAT; US-PGPUB	2004/03/18 16:02
13	236451	mold	USPAT; US-PGPUB	2004/03/18 16:02
14	5283	mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))	USPAT; US-PGPUB	2004/03/18 16:52
15	867	((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.	USPAT; US-PGPUB	2004/03/18 16:52
16	1506398	metal conductive	USPAT; US-PGPUB	2004/03/18 16:04
17	76933	mold\$3 with (metal conductive)	USPAT; US-PGPUB	2004/03/18 16:05
18	209	((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))	USPAT; US-PGPUB	2004/03/18 16:47
19	548771	carrier	USPAT; US-PGPUB	2004/03/18 16:06
20	64	((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))) and carrier	USPAT; US-PGPUB	2004/03/18 16:07
21	145	(((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))) not (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))) and carrier)	USPAT; US-PGPUB	2004/03/18 16:30
22	1256	(mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))	USPAT; US-PGPUB	2004/03/18 16:52
23	230	((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 438/\$.ccls.	USPAT; US-PGPUB	2004/03/18 17:00
24	97	(((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 438/\$.ccls.) not (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))))	USPAT; US-PGPUB	2004/03/18 16:53
25	111	((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 216/\$.ccls.	USPAT; US-PGPUB	2004/03/18 17:00